

30V N-Channel and P-Channel MOSFET

Features

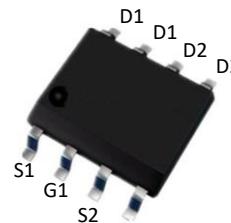
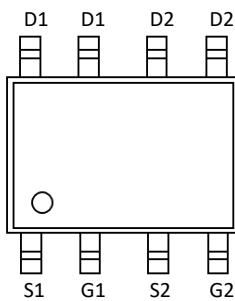
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Product Summary

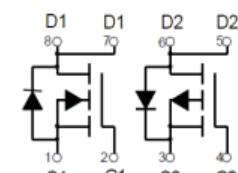
V_{DS}	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
30V	30mΩ@10V	6A
	42mΩ@4.5V	
-30V	50mΩ@-10V	-4.5A
	70mΩ@-4.5V	

Application

- Battery protection
- Load switch
- Power management



SOP-8 top view



Schematic diagram



Halogen-Free

Marking and pin assignment

Absolute Maximum Ratings ($TA=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Unit
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Common Ratings ($TC=25^\circ\text{C}$ Unless Otherwise Noted)

V_{DS}	Drain-Source Breakdown Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
T_J	Maximum Junction Temperature	150	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
I_S	Diode Continuous Forward Current	Tc=25°C 6	-4.5	A

Mounted on Large Heat Sink

I_{DM}	Pulse Drain Current Tested	Tc=25°C 33	-28	A
I_D	Continuous Drain Current@GS=10V	Tc=25°C 6	-4.5	A
P_D	Maximum Power Dissipation	Tc=25°C 2	2	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient((*1 in2 Pad of 2-oz Copper), Max.)	50	50	°C/W

N-Ch Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)						
$BV_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$VDS=30V, VGS=0V$	--	--	1	uA
I_{GSS}	Gate-Body Leakage Current	$VGS=\pm 20V, VDS=0V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1	1.5	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$VGS=10V, ID=5.6A$	--	19	30	mΩ
		$VGS=4.5V, ID=5A$	--	26	42	

Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated)

C_{ISS}	Input Capacitance	VDS=10V, VGS=0V, f=1MHz	--	632	--	pF
C_{OSS}	Output Capacitance		--	58	--	pF
C_{RSS}	Reverse Transfer Capacitance		--	70	--	pF

Switching Characteristics

Q_g	Total Gate Charge	VDS=15V, ID=3.6A, VGS=10V	--	17	--	nC
Q_{gs}	Gate Source Charge		--	2	--	nC
Q_{gd}	Gate Drain Charge		--	2	--	nC
$t_{d(on)}$	Turn-on Delay Time	VDS=15V, RL=4.1Ω, VGS=10V, RG=3Ω	--	4.5	--	nS
t_r	Turn-on Rise Time		--	28.5	--	nS
$t_{d(off)}$	Turn-Off Delay Time		--	16.5	--	nS
t_f	Turn-Off Fall Time		--	26	--	nS

Source- Drain Diode Characteristics

V_{SD}	Forward on voltage	$T_j=25^\circ C, I_s=5.6A,$	--	--	1.2	V
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P-Ch Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
BV _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, ID=-250μA	-30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , ID=-250μA	-1	-1.5	-2.5	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-10V, ID=-4.2A	--	39	50	mΩ
		V _{GS} =-4.5V, ID=-3.5A	--	52	70	

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

C _{ISS}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	--	770	--	pF
C _{OSS}	Output Capacitance		--	440	--	pF
C _{RSS}	Reverse Transfer Capacitance		--	123	--	pF

Switching Characteristics

Q _g	Total Gate Charge	V _{DS} =-10V, ID=-4.2A, V _{GS} =-15V	--	30	--	nC
Q _{gs}	Gate Source Charge		--	2.7	--	nC
Q _{gd}	Gate Drain Charge		--	6.9	--	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =-15V, ID=-1A, V _{GS} =-10V, RG=2.5Ω	--	9	--	nS
t _r	Turn-on Rise Time		--	16	--	nS
t _{d(off)}	Turn-Off Delay Time		--	77	--	nS
t _f	Turn-Off Fall Time		--	40	--	nS

Source- Drain Diode Characteristics

V _{SD}	Forward on voltage	T _J =25°C, I _S =-4.2A,	--	--	-1.2	V
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N-Channel Typical Operating Characteristics

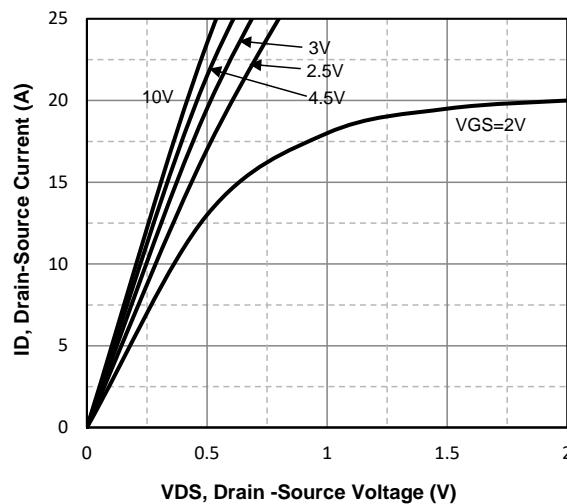


Fig1. Typical Output Characteristics

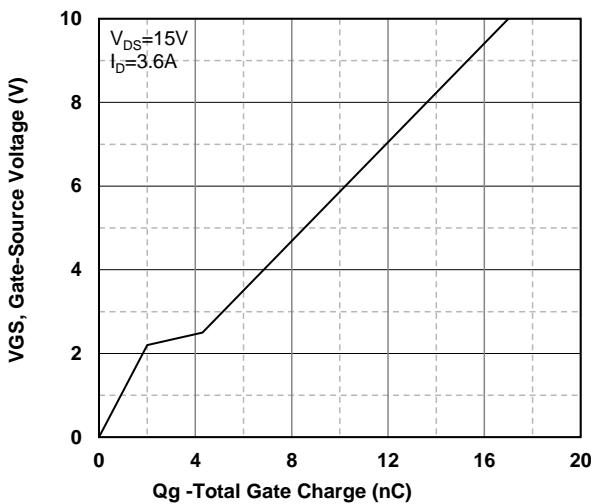


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

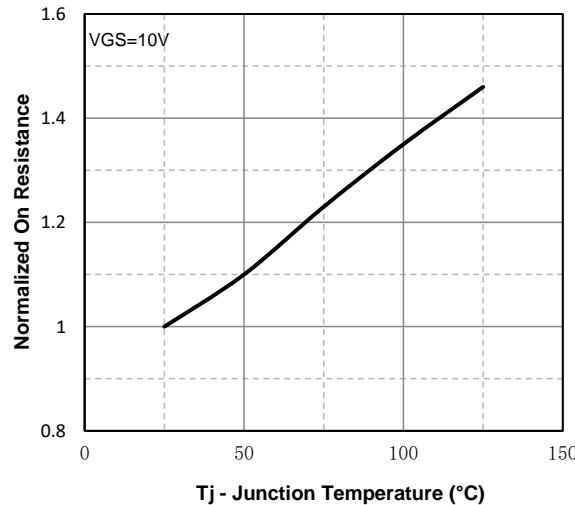


Fig3. Normalized On-Resistance Vs. Temperature

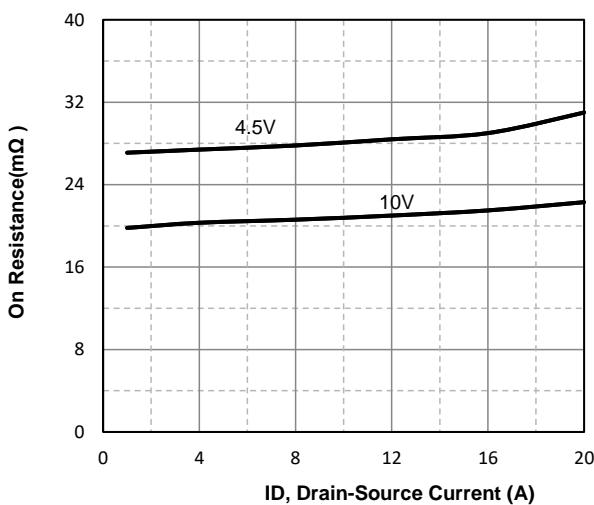


Fig4. On-Resistance Vs. Drain-Source Current

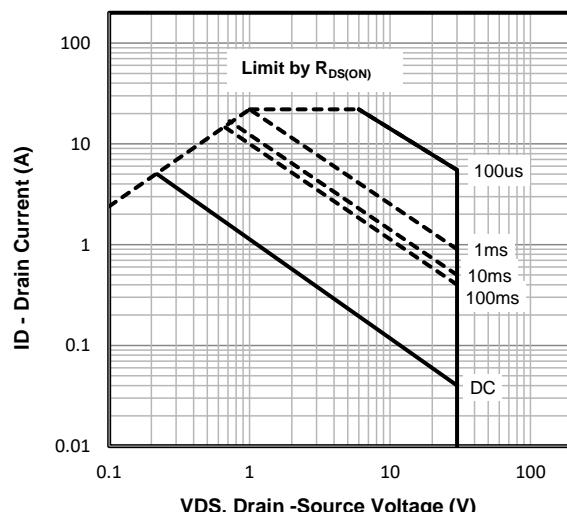


Fig5. Maximum Safe Operating Area

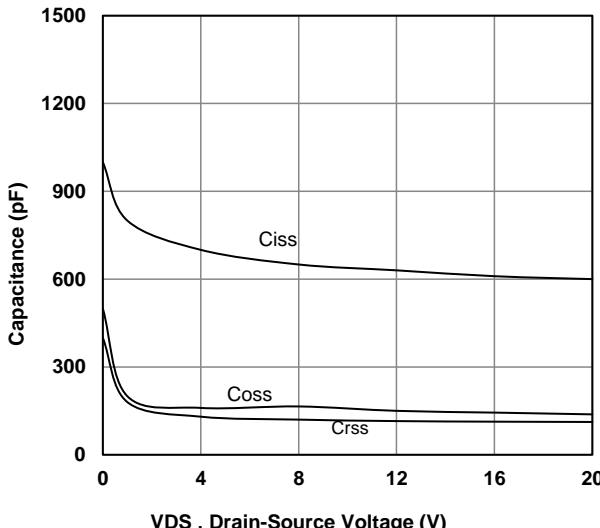


Fig6 Typical Capacitance Vs.Drain-Source Voltage

P-Channel Typical Operating Characteristics

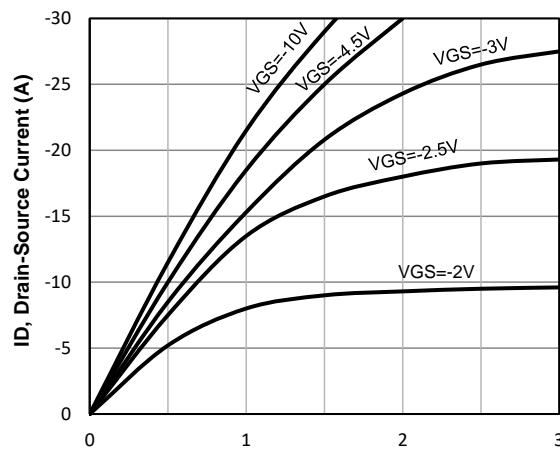


Fig1. Typical Output Characteristics

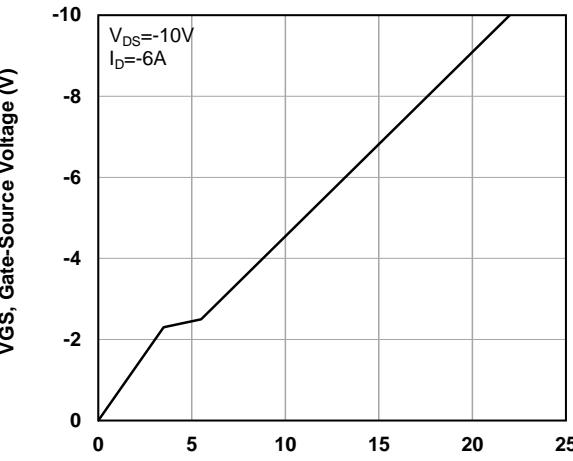


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

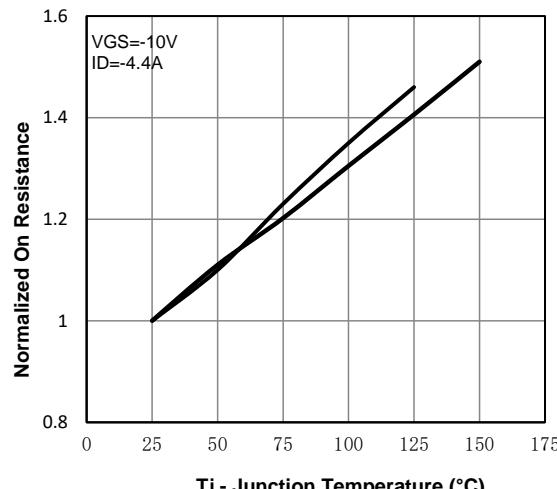


Fig3. Normalized On-Resistance Vs. Temperature

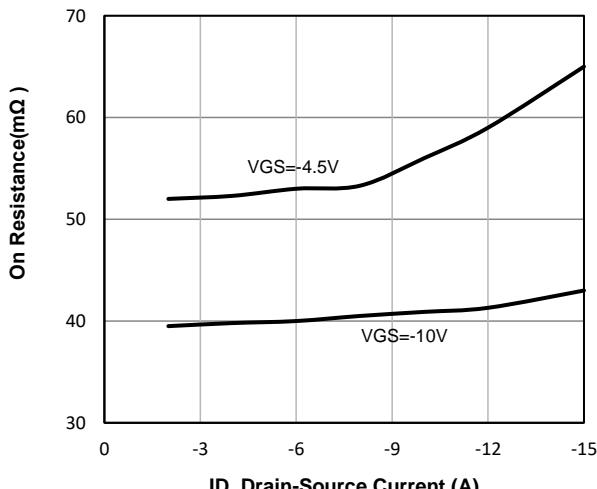


Fig4. On-Resistance Vs. Drain-Source Current

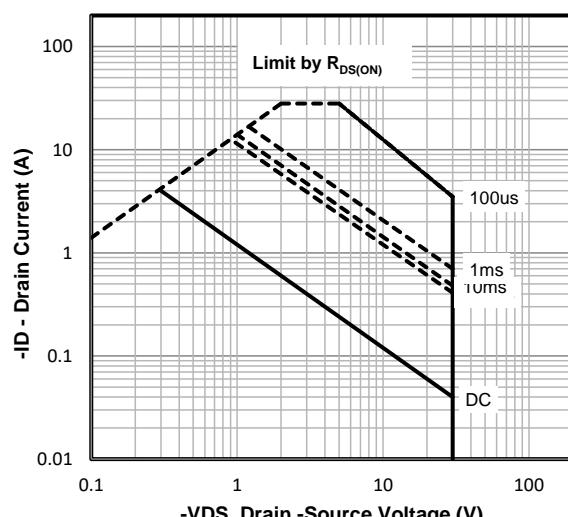


Fig5. Maximum Safe Operating Area

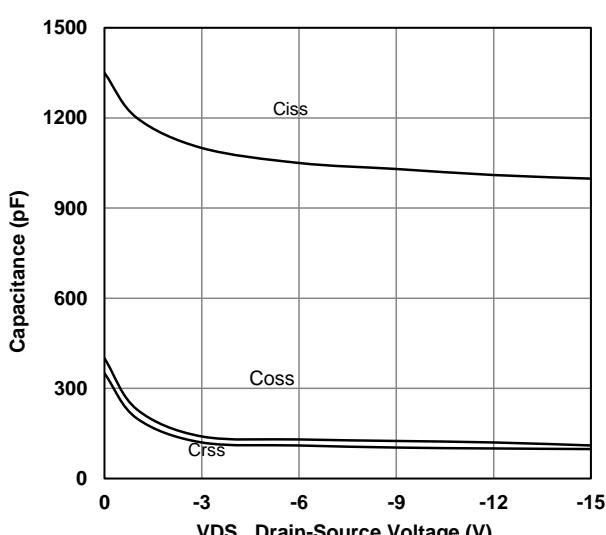
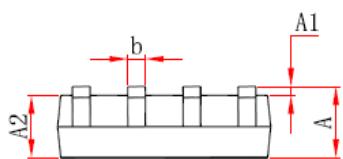
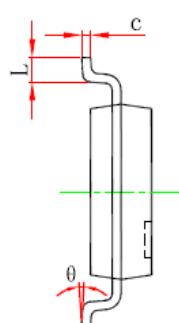
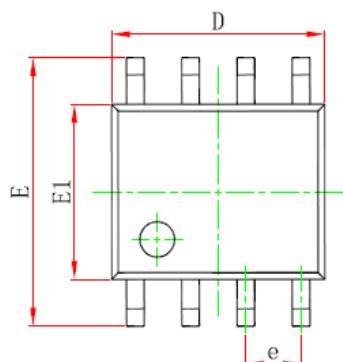


Fig6 Typical Capacitance Vs.Drain-Source Voltage

SOP-8 Package information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.450	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°